

Key Features

D.O.T. Non- Hazardous
 Electrically Isolating
 High Glass Transition Temperature
 High Temperature Resistant
 High Thermal Conductivity
 Low Shrinkage
 Flowable

Uncured

Pot Life @ 25°C: 3 hours
 Viscosity @ 25°C: 100,000 cPs
 Shelf Life @ -40°C: 12 Months (Cryo-Pac®)
 Shelf Life @ 25°C: 12 Months (Appli-Pac®)
 Mix Ratio 100A : 2.38B Parts By Weight

Cure Options

2 hours @ 80°C
 4 hours @ 60°C

Cured Properties

(Based on cure of 2 hours @ 80°C)
 Color Black
 Shore D Hardness 90
 Glass Transition Temp(°C) 100
 Density (g/cc) 2.46
 Lap Shear 2024T3 Clad (psi) 2,000
 Shrinkage Linear (%) 0.17

(Based on cure of 4 hours @ 60°C)
 Shrinkage Linear (%) 0.04

Electrical Properties

(Based on cure of 2 hours @ 80°C)
 Dielectric Constant 5.5 @ 100 kHz
 Dissipation Factor 0.01 @ 100 kHz
 Dielectric Strength (volts/mil) 445
 Volume Resistivity (ohm-cm) 4.0E 15 @ 500 VDC

Product Description:

5308 is a black, flowable, low linear shrinkage, electrically isolating, thermally conductive epoxy designed specifically for underfilling, staking and encapsulating electronics on circuit boards as well as potting and encapsulating power supplies, transformers, and coils. This material features a long work life and is ideal for applications requiring self leveling, thermal conductivity, electrical isolation and resistance to solvents and chemicals. 5308 is environmentally friendly and is considered non-hazardous per D.O.T. regulations.

Thermal Properties

(Based on cure of 2 hours @ 80°C)
 Coefficient of Thermal Expansion, ppm/°C
 Below Tg 33
 Above Tg 103
 Degradation Temp. (°C) 300
 Thermal Conductivity (W/mK) 1.26

Outgassing Properties

(Based on cure of 2 hours @ 80°C)
 TML (%) 0.12
 CVCM (%) 0.01
 WVR (%) 0.04

Acoustic Properties

Velocity (m/s) 3,124
 Impedance (MRayles) 7.69
 Loss (dB/cm-MHz) -7.71
 Density (g/cc) 2.46

The data contained herein is provided for informational purposes only and are believed to be reliable. APPLI-TEC does not guarantee suitability of this product for any resultant application or freedom from patent infringement. Furthermore, APPLI-TEC disclaims any liability for incidental and consequential damages of any kind including but not limited to lost profits.